



EM MICROELECTRONIC-MARIN SA

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Process Change Notification

PCN: 19-005

Date: Mar 15th, 2019

Part numbers affected: EM4237V1WS6E
EM4237SLICV1WS6E
EM4237SLIXV1WS6E

Technology or Product Family affected: EM4237
Package Type(s) affected: Bare die, sawn wafers on blue tape
Process step(s) affected: IC design
Mfg. facilities affected: None
Advanced notification ☒ Final notification ☐

Proposed change:
IC design based on design version "Di06".
Commercial denomination changes V1 to V3

Reason for change: Remove parasitic coupling in the test pads, causing ESD sensitivity in flip chip assembly.

Date change effective: Available now

Date old product no longer available: Oct 1st, 2019.

Remarks

If the customer has not replied within 30 days of mailing the PCN, it will be interpreted as approval.

Date: 09/04/2019

Signed:

Name:

Function: BU Leader

for and on behalf of EM Microelectronic-Marine SA, CH-2074 Marin, Switzerland

Customer Support Manager

Distribution (after signature): BU Leader, Logistics, Production

Part numbers affected:

EM Ref.	Commercial Ref (V1)	New Commercial Ref (V3)
IC-5699	EM4237V1WS6E	EM4237V3WS6E
IC-5706	EM4237SLICV1WS6E	EM4237SLICV3WS6E
IC-5842	EM4237SLIXV1WS6E	EM4237SLIXV3WS6E

DESCRIPTION OF CHANGE

IC layout changes of metal interconnect layers around 3 test pads.

Reduction of parasitic coupling between the residual test pad connection and circuitry adjacent to pad.

No change to the 2 coil pads connected to antenna.

No change to product specification or functionality.

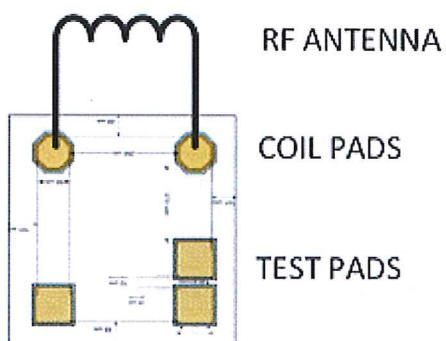
No change to product parametric performance.

IC CONNECTION SCHEME

V1

V3

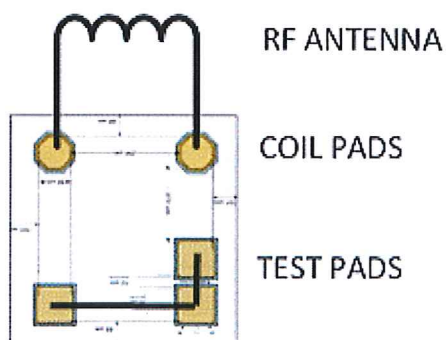
1.



OK

OK

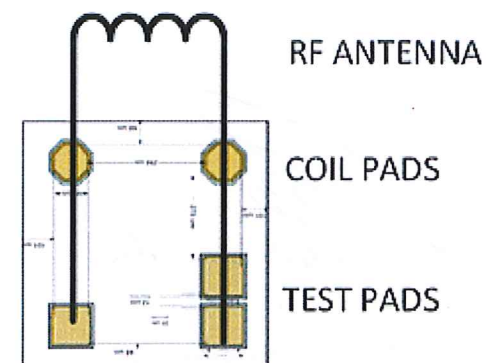
2.



ESD risk
during IC
assembly

OK

3.



ESD risk
during IC
assembly

OK